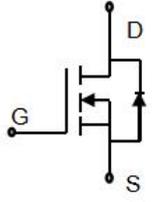


Lonten N-channel 40V, 120A, 2.8mΩ Power MOSFET

| | | | | | | | |
|--|--|-----------|-----|-------------------------------|-------|-------|------|
| <p>Description These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.</p> <p>Features</p> <ul style="list-style-type: none"> ◆ 40V,120A, $R_{DS(on),max} = 2.8m\Omega @ V_{GS} = 10V$ ◆ Improved dv/dt capability ◆ Fast switching ◆ 100% EAS Guaranteed ◆ Green device available <p>Applications</p> <ul style="list-style-type: none"> ◆ Motor Drives ◆ UPS ◆ DC-DC Converter | <p>Product Summary</p> <table style="width: 100%; border: none;"> <tr> <td style="padding: 2px;">V_{DSS}</td> <td style="padding: 2px;">40V</td> </tr> <tr> <td style="padding: 2px;">$R_{DS(on),max} @ V_{GS}=10V$</td> <td style="padding: 2px;">2.8mΩ</td> </tr> <tr> <td style="padding: 2px;">I_D</td> <td style="padding: 2px;">120A</td> </tr> </table> <p>Pin Configuration</p> <div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;">  TO-251 </div> <div style="text-align: center;">  TO-252 </div> </div> <div style="text-align: right; margin-top: 20px;">  </div> <p style="text-align: center; margin-top: 20px;">N-Channel MOSFET </p> | V_{DSS} | 40V | $R_{DS(on),max} @ V_{GS}=10V$ | 2.8mΩ | I_D | 120A |
| V_{DSS} | 40V | | | | | | |
| $R_{DS(on),max} @ V_{GS}=10V$ | 2.8mΩ | | | | | | |
| I_D | 120A | | | | | | |

Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

| Parameter | Symbol | Value | Unit |
|---|-----------|-------------|------|
| Drain-Source Voltage | V_{DSS} | 40 | V |
| Continuous drain current ($T_C = 25^\circ C$) ¹⁾ | I_D | 120 | A |
| Continuous drain current ($T_C = 100^\circ C$) | | 81 | A |
| Pulsed drain current ²⁾ | I_{DM} | 360 | A |
| Gate-Source voltage | V_{GSS} | ±18 | V |
| Avalanche energy ³⁾ | E_{AS} | 225 | mJ |
| Power Dissipation ($T_C = 25^\circ C$) | P_D | 57.6 | W |
| Storage Temperature Range | T_{STG} | -55 to +150 | °C |
| Operating Junction Temperature Range | T_J | -55 to +150 | °C |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--------------------------------------|-----------------|-------|------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 1.67 | °C/W |

Package Marking and Ordering Information

| Device | Device Package | Marking |
|------------|----------------|------------|
| LSGH04R028 | TO-251 | LSGH04R028 |
| LSGG04R028 | TO-252 | LSGG04R028 |

Electrical Characteristics
 $T_J = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Test Condition | Min. | Typ. | Max. | Unit |
|---|--------------|---|------|------|------|---------------|
| Static characteristics | | | | | | |
| Drain-source breakdown voltage | BV_{DSS} | $V_{GS}=0\text{ V}, I_D=250\mu\text{A}$ | 40 | --- | --- | V |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu\text{A}$ | 1.0 | --- | 2.2 | V |
| Drain-source leakage current | I_{DSS} | $V_{DS}=40\text{ V}, V_{GS}=0\text{ V}, T_J=25^\circ\text{C}$ | --- | --- | 1 | μA |
| Gate leakage current, Forward | I_{GSSF} | $V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$ | --- | --- | 100 | nA |
| Gate leakage current, Reverse | I_{GSSR} | $V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$ | --- | --- | -100 | nA |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=10\text{ V}, I_D=50\text{ A}$ | --- | --- | 2.8 | m Ω |
| | | $V_{GS}=4.5\text{ V}, I_D=20\text{ A}$ | --- | --- | 5.3 | m Ω |
| Forward transconductance | g_{fs} | $V_{DS}=10\text{ V}, I_D=20\text{ A}$ | --- | 131 | --- | S |
| Dynamic characteristics | | | | | | |
| Input capacitance | C_{iss} | $V_{DS}=15\text{ V}, V_{GS}=0\text{ V},$ $F=1\text{ MHz}$ | --- | 3210 | --- | pF |
| Output capacitance | C_{oss} | | --- | 2130 | --- | |
| Reverse transfer capacitance | C_{rss} | | --- | 343 | --- | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}=15\text{ V}, V_{GS}=10\text{ V}, I_D=20\text{ A}$ $R_G=1.6\Omega$ | --- | 9 | --- | ns |
| Rise time | t_r | | --- | 4 | --- | |
| Turn-off delay time | $t_{d(off)}$ | | --- | 45 | --- | |
| Fall time | t_f | | --- | 7 | --- | |
| Gate charge characteristics | | | | | | |
| Gate to source charge | Q_{gs} | $V_{DS}=15\text{ V}, I_D=15\text{ A},$ $V_{GS}=10\text{ V}$ | --- | 7 | --- | nC |
| Gate to drain charge | Q_{gd} | | --- | 17.5 | --- | |
| Gate charge total | Q_g | | --- | 67 | --- | |
| Drain-Source diode characteristics and Maximum Ratings | | | | | | |
| Continuous Source Current | I_S | | --- | --- | 120 | A |
| Pulsed Source Current ⁴⁾ | I_{SM} | | --- | --- | 360 | A |
| Diode Forward Voltage | V_{SD} | $V_{GS}=0\text{ V}, I_S=40\text{ A}, T_J=25^\circ\text{C}$ | --- | 0.85 | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $I_S=I_F, di/dt=100\text{ A}/\mu\text{s}, T_J=25^\circ\text{C}$ ⁵⁾ | --- | --- | 26 | ns |
| Reverse Recovery Charge | Q_{rr} | | --- | --- | 95 | nC |

Notes:

- 1: The maximum junction current rating is package limited.
- 2: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3: $V_{DD}=23\text{ V}, V_{GS}=10\text{ V}, L=0.5\text{ mH}, I_{AS}=30\text{ A}, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
- 4: Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.
- 5: Guaranteed by design, not subject to production.

Electrical Characteristics Diagrams

Fig 1: Output Characteristics

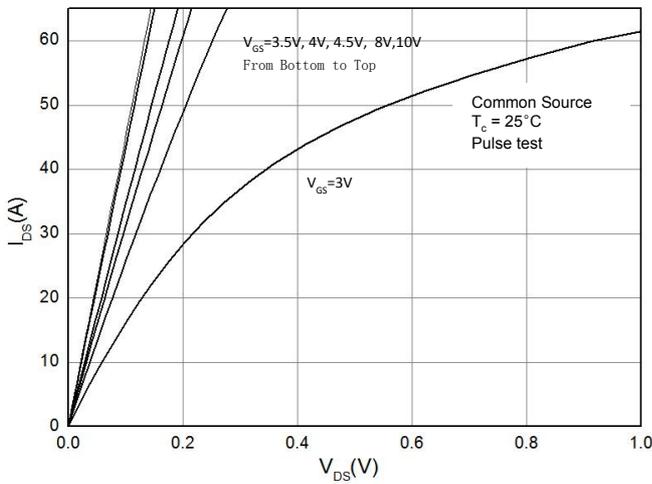


Fig 2: Transfer Characteristics

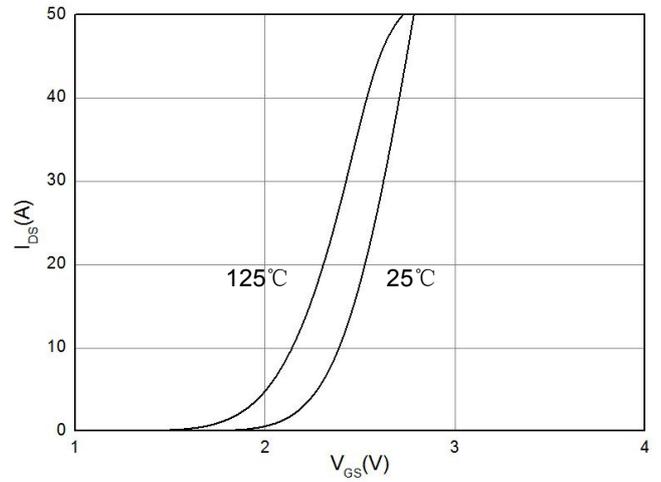


Figure 3. Capacitance Characteristics

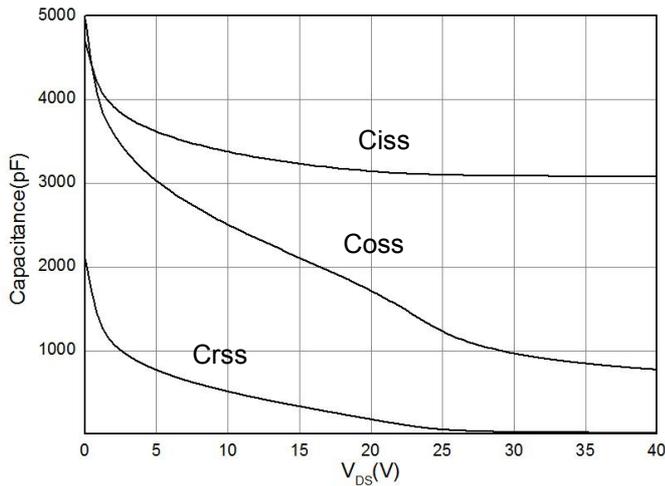


Figure 4. Gate Charge Waveform

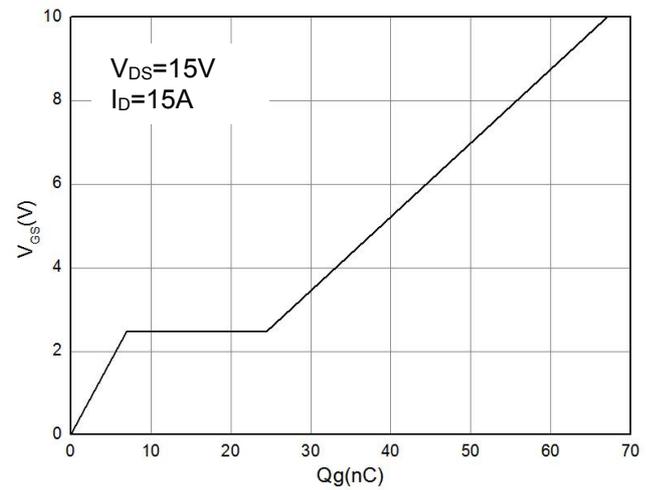


Figure 5. Body-Diode Characteristics

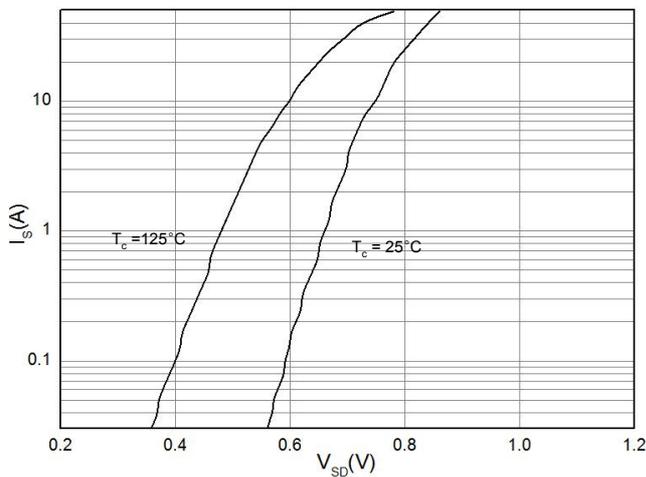


Figure 6. Rds(on)-Drain Current

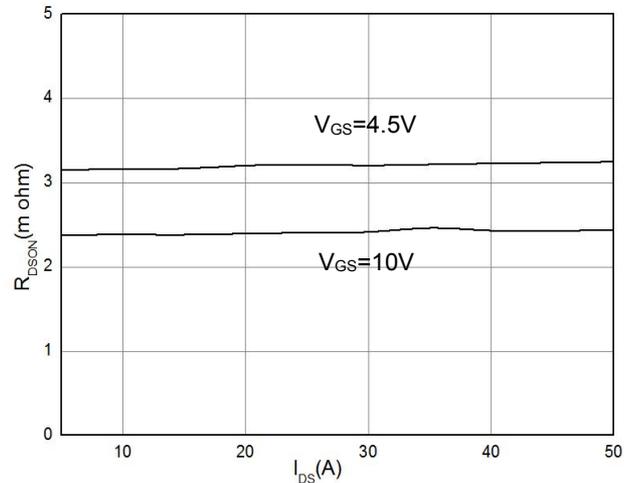


Fig 7: Rds(on) vs Gate Voltage

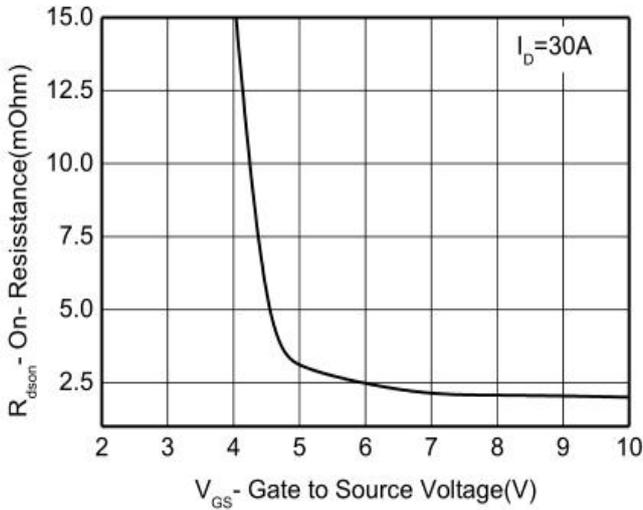


Fig 8: Rds(on)-Junction Temperature(°C)

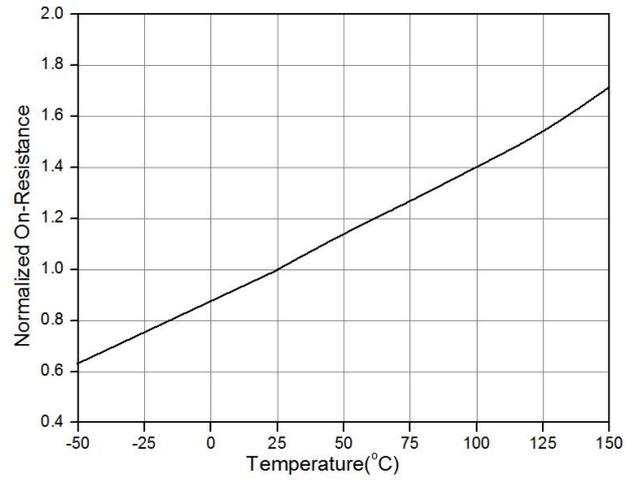


Figure 9. BVdss vs. Junction temperature

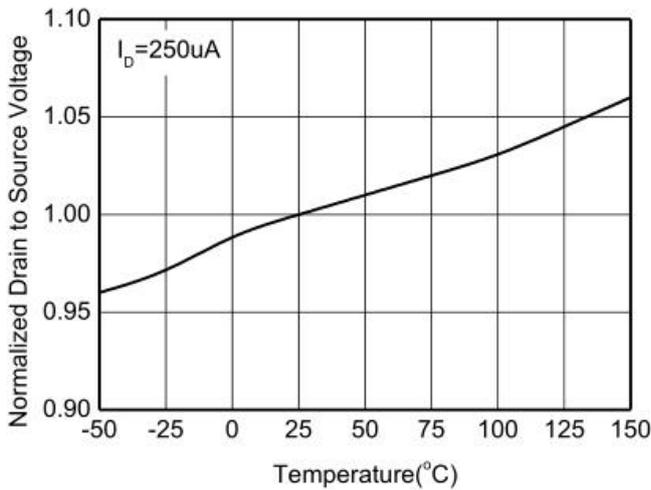


Figure 10. Maximum Safe Operating Area

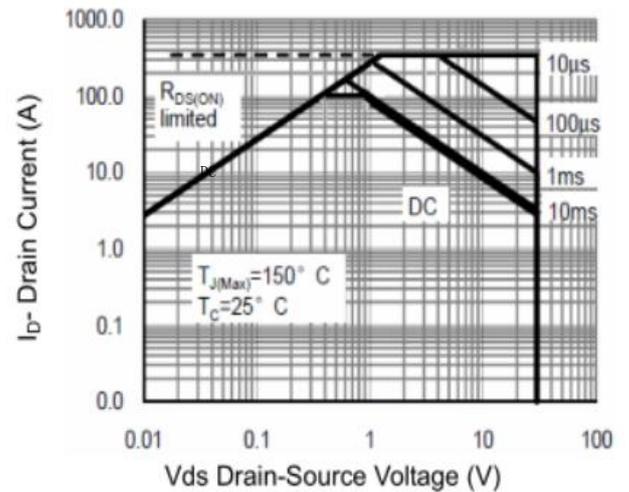
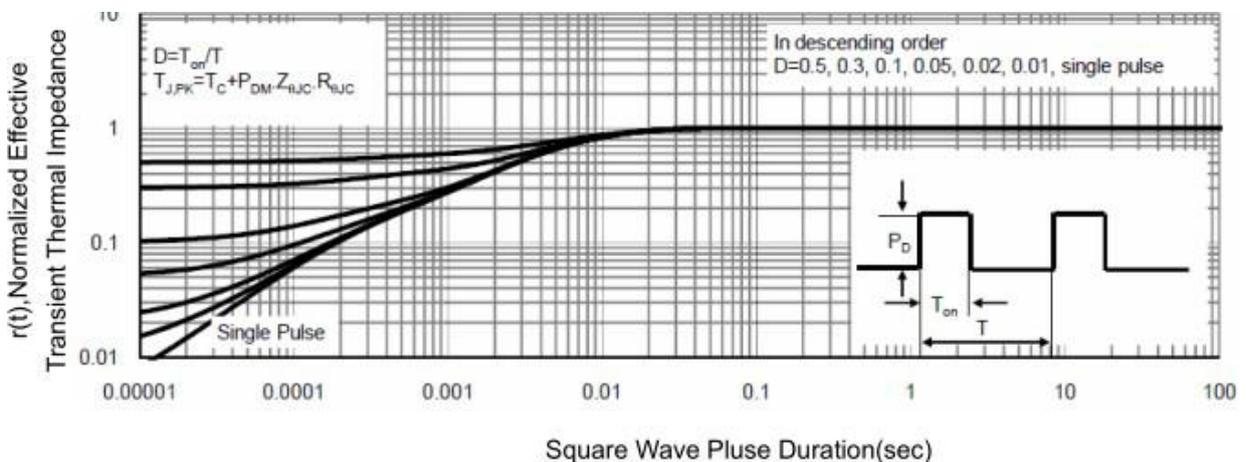


Figure 11. Normalized Maximum Transient Thermal Impedance (RthJC)



Test Circuit & Waveform

Figure 12. Gate Charge Test Circuit & Waveform

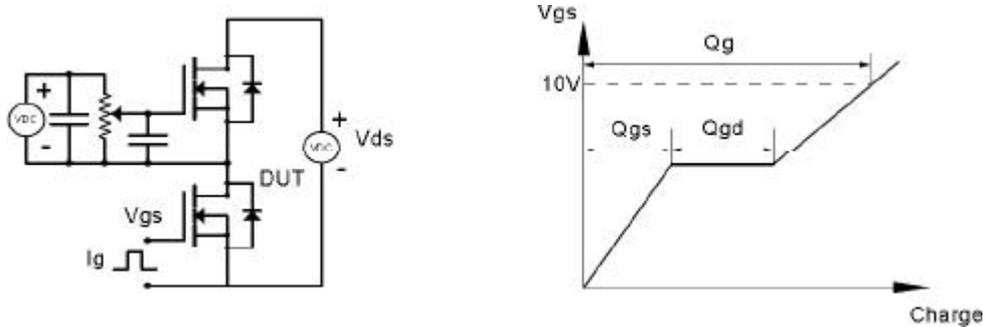


Figure 13. Resistive Switching Test Circuit & Waveforms

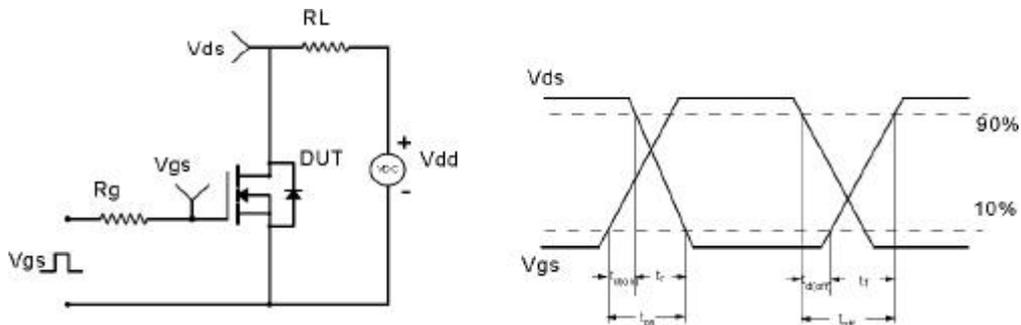


Figure 14. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

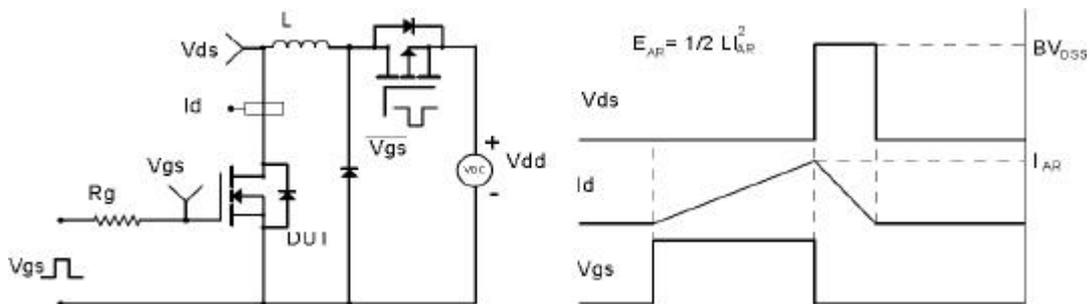
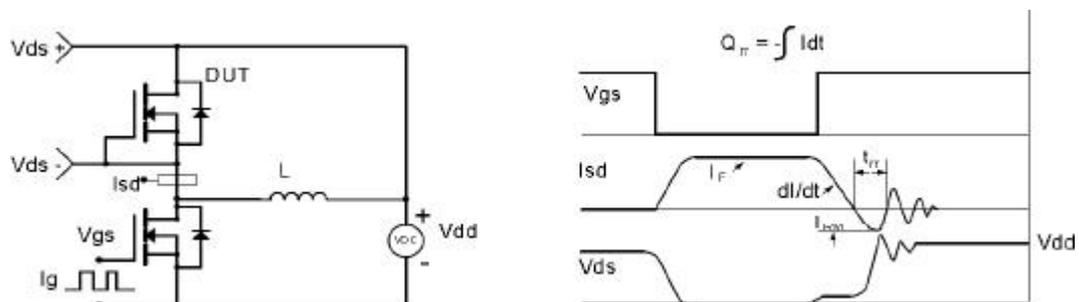
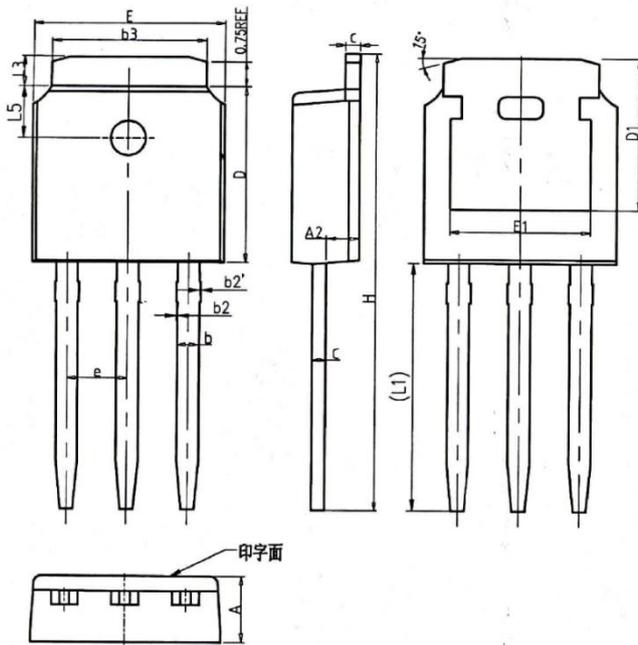


Figure 15. Diode Recovery Circuit & Waveform

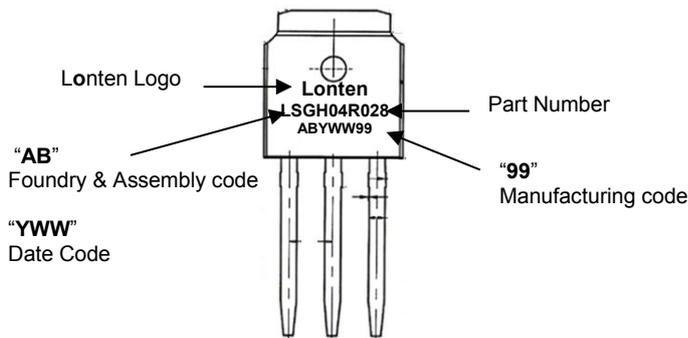


Mechanical Dimensions for TO-251



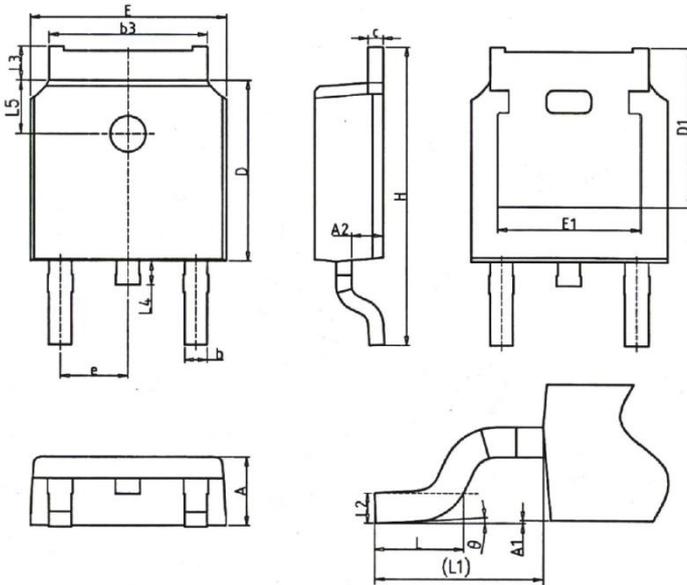
| COMMON DIMENSIONS | | | | | | |
|-------------------|----------|-------|-------|----------|-------|-------|
| SYMBOL | MM | | | INCH | | |
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 2.20 | 2.30 | 2.38 | 0.087 | 0.091 | 0.094 |
| A2 | 0.97 | 1.07 | 1.17 | 0.038 | 0.042 | 0.046 |
| b | 0.68 | 0.78 | 0.90 | 0.027 | 0.031 | 0.035 |
| b2 | 0.00 | 0.04 | 0.10 | 0.000 | 0.002 | 0.004 |
| b2' | 0.00 | 0.04 | 0.10 | 0.000 | 0.002 | 0.004 |
| b3 | 5.20 | 5.33 | 5.46 | 0.205 | 0.210 | 0.215 |
| c | 0.43 | 0.53 | 0.61 | 0.017 | 0.021 | 0.024 |
| D | 5.98 | 6.10 | 6.22 | 0.235 | 0.240 | 0.245 |
| D1 | 5.30REF | | | 0.209REF | | |
| E | 6.40 | 6.60 | 6.73 | 0.252 | 0.260 | 0.265 |
| E1 | 4.63 | - | - | 0.182 | - | - |
| e | 2.286BSC | | | 0.090BSC | | |
| H | 16.22 | 16.52 | 16.82 | 0.639 | 0.650 | 0.662 |
| L1 | 9.15 | 9.40 | 9.65 | 0.360 | 0.370 | 0.380 |
| L3 | 0.88 | 1.02 | 1.28 | 0.035 | 0.040 | 0.050 |
| L5 | 1.65 | 1.80 | 1.95 | 0.065 | 0.071 | 0.077 |

TO-251 Part Marking Information



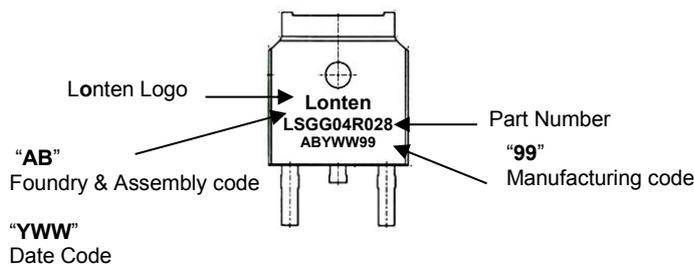
| Calendar Year | Year Code | Calendar Week | Week Code |
|---------------|-----------|---------------|-----------|
| 2018 | G | Workweek 01 | 01 |
| 2019 | H | Workweek 02 | 02 |
| 2020 | I | Workweek 03 | 03 |
| 2021 | J | Workweek 04 | 04 |
| 2022 | K | Workweek 05 | 05 |
| 2023 | L | Workweek 06 | 06 |
| 2024 | M | | |

Mechanical Dimensions for TO-252



| SYMBOL | COMMON DIMENSIONS | | | | | |
|--------|-------------------|-------|-------|----------|-------|-------|
| | MM | | | INCH | | |
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 2.20 | 2.30 | 2.38 | 0.087 | 0.091 | 0.094 |
| A1 | 0.00 | - | 0.20 | 0.000 | - | 0.008 |
| A2 | 0.97 | 1.07 | 1.17 | 0.038 | 0.042 | 0.046 |
| b | 0.68 | 0.78 | 0.90 | 0.027 | 0.031 | 0.035 |
| b3 | 5.20 | 5.33 | 5.46 | 0.205 | 0.210 | 0.215 |
| c | 0.43 | 0.53 | 0.61 | 0.017 | 0.021 | 0.024 |
| D | 5.98 | 6.10 | 6.22 | 0.235 | 0.240 | 0.245 |
| D1 | 5.30REF | | | 0.209REF | | |
| E | 6.40 | 6.60 | 6.73 | 0.252 | 0.260 | 0.265 |
| E1 | 4.63 | - | - | 0.182 | - | - |
| e | 2.286BSC | | | 0.090BSC | | |
| H | 9.40 | 10.10 | 10.50 | 0.370 | 0.398 | 0.413 |
| L | 1.38 | 1.50 | 1.75 | 0.054 | 0.059 | 0.069 |
| L1 | 2.90REF | | | 0.114REF | | |
| L2 | 0.51BSC | | | 0.020BSC | | |
| L3 | 0.88 | - | 1.28 | 0.035 | - | 0.050 |
| L4 | 0.50 | - | 1.00 | 0.020 | - | 0.039 |
| L5 | 1.65 | 1.80 | 1.95 | 0.065 | 0.071 | 0.077 |
| θ | 0° | - | 8° | 0° | - | 8° |

TO-252 Part Marking Information



| Calendar Year | Year Code | Calendar Week | Week Code |
|---------------|-----------|---------------|-----------|
| 2018 | G | Workweek 01 | 01 |
| 2019 | H | Workweek 02 | 02 |
| 2020 | I | Workweek 03 | 03 |
| 2021 | J | Workweek 04 | 04 |
| 2022 | K | Workweek 05 | 05 |
| 2023 | L | Workweek 06 | 06 |
| 2024 | M | | |

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